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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/388,031	09/01/1999	SALMAN AKRAM	3442US(96-42	3303
7590	11/16/2004		EXAMINER	
TRASK BRITT & ROSSA PO BOX 2550 SALT LAKE CITY, UT 84110				LEE, EUGENE
			ART UNIT	PAPER NUMBER
			2815	

DATE MAILED: 11/16/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

207

<b>Advisory Action</b>	<b>Application No.</b>	<b>Applicant(s)</b>
	09/388,031	AKRAM, SALMAN*
	<b>Examiner</b>	<b>Art Unit</b>
	Eugene Lee	2815

--The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

THE REPLY FILED 25 October 2004 FAILS TO PLACE THIS APPLICATION IN CONDITION FOR ALLOWANCE. Therefore, further action by the applicant is required to avoid abandonment of this application. A proper reply to a final rejection under 37 CFR 1.113 may only be either: (1) a timely filed amendment which places the application in condition for allowance; (2) a timely filed Notice of Appeal (with appeal fee); or (3) a timely filed Request for Continued Examination (RCE) in compliance with 37 CFR 1.114.

**PERIOD FOR REPLY [check either a) or b)]**

- a)  The period for reply expires 3 months from the mailing date of the final rejection.
- b)  The period for reply expires on: (1) the mailing date of this Advisory Action, or (2) the date set forth in the final rejection, whichever is later. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of the final rejection.  
ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS FILED WITHIN TWO MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f).

Extensions of time may be obtained under 37 CFR 1.136(a). The date on which the petition under 37 CFR 1.136(a) and the appropriate extension fee have been filed is the date for purposes of determining the period of extension and the corresponding amount of the fee. The appropriate extension fee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened statutory period for reply originally set in the final Office action; or (2) as set forth in (b) above, if checked. Any reply received by the Office later than three months after the mailing date of the final rejection, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

1.  A Notice of Appeal was filed on \_\_\_\_\_. Appellant's Brief must be filed within the period set forth in 37 CFR 1.192(a), or any extension thereof (37 CFR 1.191(d)), to avoid dismissal of the appeal.
2.  The proposed amendment(s) will not be entered because:
  - (a)  they raise new issues that would require further consideration and/or search (see NOTE below);
  - (b)  they raise the issue of new matter (see Note below);
  - (c)  they are not deemed to place the application in better form for appeal by materially reducing or simplifying the issues for appeal; and/or
  - (d)  they present additional claims without canceling a corresponding number of finally rejected claims.

NOTE: \_\_\_\_\_.

3.  Applicant's reply has overcome the following rejection(s): \_\_\_\_\_.
4.  Newly proposed or amended claim(s) \_\_\_\_\_ would be allowable if submitted in a separate, timely filed amendment canceling the non-allowable claim(s).
5.  The a) affidavit, b) exhibit, or c) request for reconsideration has been considered but does NOT place the application in condition for allowance because: See Continuation Sheet.
6.  The affidavit or exhibit will NOT be considered because it is not directed SOLELY to issues which were newly raised by the Examiner in the final rejection.
7.  For purposes of Appeal, the proposed amendment(s) a) will not be entered or b) will be entered and an explanation of how the new or amended claims would be rejected is provided below or appended.

The status of the claim(s) is (or will be) as follows:

Claim(s) allowed: \_\_\_\_\_.

Claim(s) objected to: \_\_\_\_\_.

Claim(s) rejected: 1-28 and 100-129.

Claim(s) withdrawn from consideration: \_\_\_\_\_.

8.  The drawing correction filed on \_\_\_\_\_ is a) approved or b) disapproved by the Examiner.

9.  Note the attached Information Disclosure Statement(s) (PTO-1449) Paper No(s). 10/25/04.

10.  Other: \_\_\_\_\_.

*Tom Thomas*  
TOM THOMAS  
EXAMINER  
SEARCHER  
TELEPHONE: (703) 305-1000  
FAX: (703) 305-0234  
E-MAIL: THOMAS.TOM@USPTO.GOV

Continuation of 5. does NOT place the application in condition for allowance because: Regarding the objection to the drawings, claim objections, and 112 rejection, the conductive layer (as disclosed by the specification) is not layer 62/64. Based on the applicant's disclosure, layer 66 is the conductive layer since it is the only layer that has an upper surface substantially coincident with an upper surface of the dielectric layer as disclosed in claim 16. As the claim is currently written, the conductive line and conductive layer are separate structures since the applicant does not state the conductive line comprising the conductive layer. Therefore, the layer 66 does not contact the metal layer 52. Regarding the 102 rejection, dependent on the 112 rejection, the disclosure still does not describe how the conductive metal is in contact with the metal layer. Regarding applicant's argument that no motivation exists to combine only the bottom barrier layer 4 of Liu without the top metal barrier layer 8 as Liu teaches the benefits of fully encapsulated copper lines, this argument is not persuasive. Liu discloses (see, for example, column 3, lines 34-38) that a bottom barrier layer 4 passivates the underside of an overlying copper layer. Liu in no way states that the bottom barrier layer must be included with the top barrier layer 8. Therefore, it would have been obvious to have the bottom barrier layer of Liu in Brennan's invention in order to passivate the bottom surface of the interconnect.